Big Data and Cloud Computing: Innovations and Challenges

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Deadline for manuscript submissions:
closed (15 January 2023)

Message from the Guest Editors

The main aim of this Special Issue is to seek high-quality submissions that highlight emerging applications with advanced technologies and address recent breakthroughs in the design of big data and cloud systems. The topics of interest include, but are not limited to:

- Resource allocation;
- Task scheduling;
- Workload load balance;
- Distributed computing architectures;
- Cloud data center networks;
- Big data analytics;
- Big data security and privacy;
- Data recovery;
- Data integrity;
- Artificial intelligence for big data and clouds;
- Energy efficiency in big data and clouds;
- Performance evaluation of big data and cloud systems;
- Pricing and accessibility of cloud resources;
- Edge cloud for big data.

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Message from the Editor-in-Chief

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